nexperia

Quarterly Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs		User Part Number						
		PHDMI2FR4						
		Part Description						
		NXP ICN8 Protection INDI MCD package						
								Test
	TEST Pre- and Post-Stress							
# 1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
# 2	PC Preconditioning	JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering	24 hours 168 hours 3 cycles	142	11435	0		
# 5	HTRB High Temperature Reverse Bias	MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage	1000 hours	18	1440	0		
# 7	TC Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	1000 cycles	53	4225	0		
# 8	AC Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)	96 hours	39	3165	0		
# 9	H3TRB High Humidity High Temperature Reverse Bias	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage ^[1]	1000 hours	51	4045	0		
# 10	IOL Intermittent Operating Life	MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj =	1000 hours	n.a.	n.a.	n.a.		
# 20	RSH Resistance to Solder Heat	JESD22-A111 260 °C ± 5 °C	10 s	n.a.	n.a.	n.a.		
# 21	SD Solderability	J-STD-002		78	780	0		

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

NXP ICN8 Protection INDI 1440 0 2.95 3.39E+08	Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
	NXP ICN8	Protection INDI	1440	0	2.95	3.39E+08

© 2022 Nexperia B.V.

All information hereunder is per Nexperia's best knowledge. This document does not provide for any nexperia.com representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.